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Microsystems- and Precision Engineering (GMM)

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In cooperation with:

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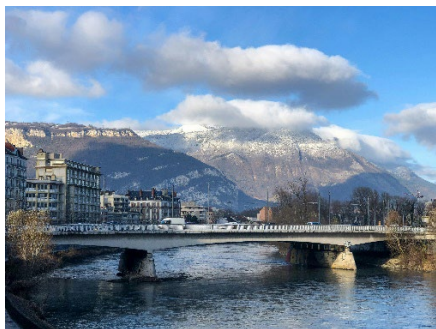
EMLC 2024 Conference Chair

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Venue: MINATEC Conference Center, Grenoble



MINATEC
Conference Center,
Grenoble



City of Grenoble at
the River Isère

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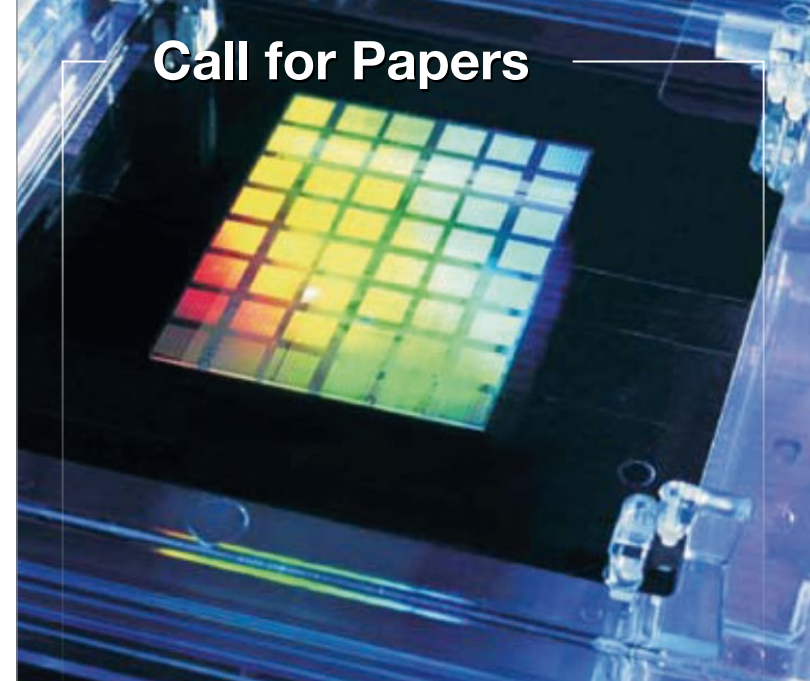
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Call for Papers

The 39th European
Mask and Lithography
Conference

EMLC 2024

June 17 – 19, 2024
MINATEC / CEA-Leti
in Grenoble, France

www.emlc-conference.com

Cover picture:
Courtesy of Toppan Photomasks

39th European Mask and Lithography
Conference, EMLC 2024
at the MINATEC Conference Center
in Grenoble, France,
June 17 – 19, 2024

The focus of this conference is state-of-the-art of mask technology and lithography, such as mask manufacturing, mask business, lithography and mask applications, emerging mask & lithography technologies, and mask & lithography equipment.

This conference has annually brought together scientists, researchers, engineers, and developers from around the world to present papers at the forefront of research, manufacturing and application. It provides a place where both specialists from industry and advanced research as well as equipment and software providers become acquainted with new developments and results.

Technical Exhibition

The conference is accompanied by a technical exhibition with booth space for about 30 exhibitors. To be part of this Technical Exhibition, please return the **registration form** to the Conference Exhibition Organization as soon as possible, since exhibition space is limited. As to the registration form, please visit the conference homepage.

Exhibition Organization

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Abstract Information

Abstract quality will be the basis for selection of conference presentations. The abstracts will be assessed for:

- Originality of work
- Specific results reported
- Potential impact and interest to the attendees.

Therefore, we highly recommend that your abstract contains enough detailed information to clearly describe the content of your presentation. An abstract with the length of **two pages** (abstract title, author*s, affiliation*s, and abstract text on the 1st page, figures on the 2nd page) as PDF file is mandatory, in addition to a maximum 100-word short abstract for the SPIE submission. Commercial papers, papers with no new research/development content, and papers where significant information is missing will not be accepted. All accepted abstracts will be made available in digital form to the conference participants.

In order to submit your abstract to SPIE, please visit the website

www.emlc-conference.com

where you can find more information as to the submission.

By submitting an abstract you agree to:

- present your work in person at the conference
- and to submit a manuscript for the SPIE Proceedings in time.

Deadline for abstracts is January 31st, 2024

Authors will be notified of the acceptance of their submissions **by Monday, April 15th, 2024**; further manuscript format and layout instructions will be provided at that time.

Please note that we plan to have oral and poster presentations.

EMLC 2024 Proceedings

Manuscripts (proceedings) will be published in the SPIE Digital Library.

Deadline for the submission of your manuscripts to SPIE is June 30th, 2024.

For further information concerning the submission procedure, please visit our homepage: www.emlc-conference.com

Conference Topics

Mask Manufacturing and Mask Business

- Mask Data Preparation
- Pattern Generation: Laser, Electron single and multi-beam mask writing
- Photomask Processes & Materials
- Metrology Tools & Technologies
- Defect Inspection & Repair
- Cleaning & Haze
- Pellicles & Mask Boxes
- Mask Process Yield & Cycle Time
- Photomasks for RET (OPC, ILT); PSM
- Mask Business and Management
- Mask Cost and Mask Development Strategy
- Future Mask Demand

Lithographic Systems and Processes

- Optical Resolution Enhancements including OPC, Free-form Illumination, Source-Mask-optimization (SMO) and Inverse Lithography Technology (ILT)
- Material-and Process driven Resolution Enhancements including Multiple Patterning and Chemical Shrinking
- Immersion Lithography including Defectivity
- Lithography Process Control
- Lithography and Etch Simulation including rigorous physical/chemical Models and Compact Models

Emerging Mask and Lithography Technologies

- EUV-Lithography including Masks, Materials Processes and Infrastructure
- Directed Self-Assembly (DSA) including High Chi Materials, Defectivity Control, and new Processes
- Direct Write / Maskless Technologies including Multi-Beam Technologies
- Nano-Imprint Lithography (NIL), Soft Lithography, and Microprinting

Emerging Applications

- Non-IC Applications including Si-Photonics, flat Panel Displays and MEMS
- Lithographic Systems for non-IC Applications, including Laser Direct Write, Interference Lithography, and Mask Aligners